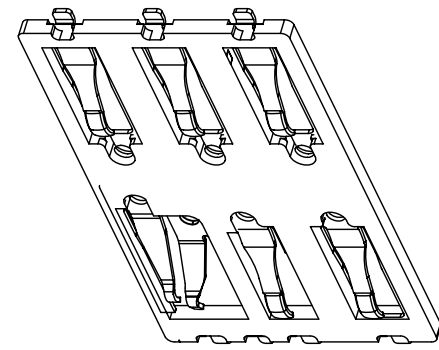
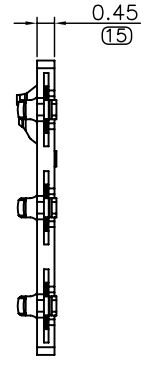
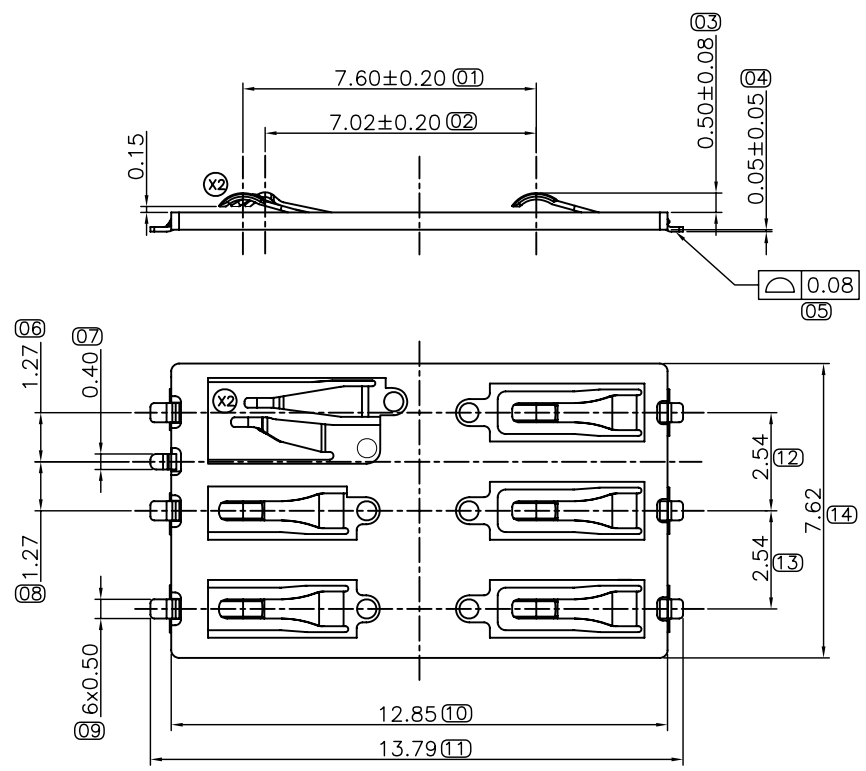
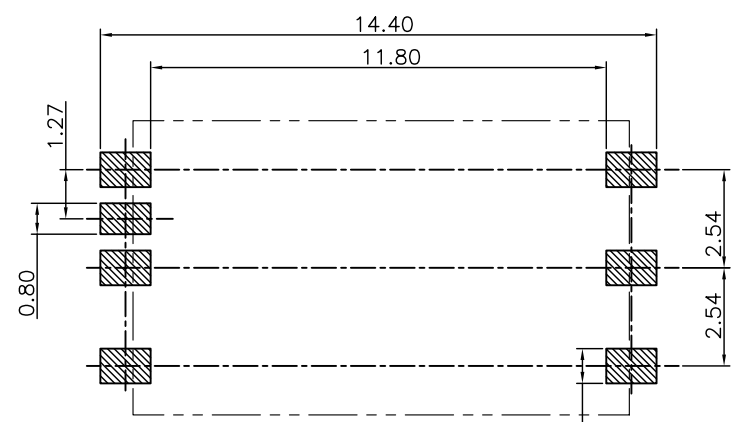


REV	ECN NO	DESCRIPTION	DATE	APPD
X1		BRAN-NEW	2013.09.12	TANLINHONG
X2	PECN1310005	客户要求修改侦测PIN头部尖端到端子面的距离	2013.10.15	TANLINHONG



NOTE:

- 1: HOUSING MATERIAL: THERMAL PLASTIC, COLOR: BLACK;
- 2: CONTACT MATERIAL: COPPER ALLOY;
- 3: PLATING:  
15u"(0.375um)Min. GOLD PLATING ON CONTACT AREA;  
100u"(2.54um)Min. MATTE-TIN PLATING ON SOLDER AREA.
- 4: PERFORMANCE:  
4.1:CONTACT RESISTANCE: 60mOHM Max.  
4.2:DIELECTRIC WITHSTANDING VOLTAGE: 200 VAC FOR 1MINUTE;  
4.3:INSULATION RESISTANCE: 1000MOHM Min.  
4.4:DURABILITY: 5000 TIMES Min.



RECOMMENDED PCB LAYOUT  
(TOLERANCE +/-0.05)

EXTEND USE		TITLE	
MICRO SIM CARD 0.5H		MICRO SIM CARD 0.5H ASSEMBLY DRAWING	
UNIT	mm	APPD	DWG NO
GENERAL TOLERANCE (1)	MATERIAL	谭林红 2013.10.15	C-1.042A0
DIMENSION	ANGLES	QTY	P/N:
. ±0.30	. ±3°	CHD 谭林红 2013.10.15	1.042A0-007-5R0
.0 ±0.25	.0 ±2°	FINISHED	DRN 黄文珠 2013.10.15
.00 ±0.20	.00 ±1°	SHEET	SCALE
.000 ±0.10		1/1	1:1
		REV	X2